

H7N0307AB

Silicon N Channel MOS FET High Speed Power Switching

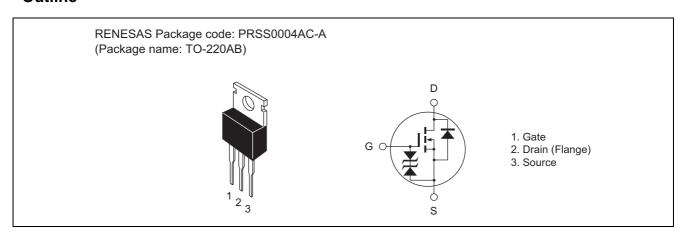
REJ03G1120-0300 (Previous: ADE-208-1568A)

> Rev.3.00 Sep 07, 2005

Features

- Low on-resistance $R_{DS\;(on)} = 4.6\; m\Omega \; typ. \label{eq:RDS}$
- Low drive current
- 4.5 V gate drive device can be driven from 5 V source

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	30	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	60	A
Drain peak current	I _{D (pulse)} Note 1	240	A
Body-drain diode reverse drain current	I _{DR}	60	A
Channel dissipation	Pch Note 2	90	W
Channel to case thermal impedance	θ ch-c	1.39	°C/W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Value at Tc = 25°C

Electrical Characteristics

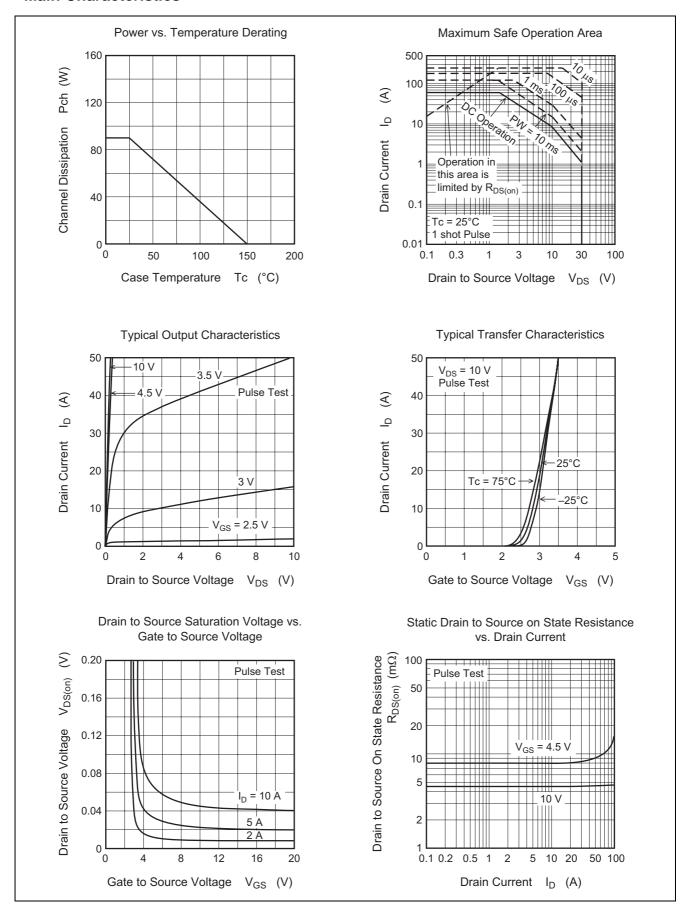
 $(Ta = 25^{\circ}C)$

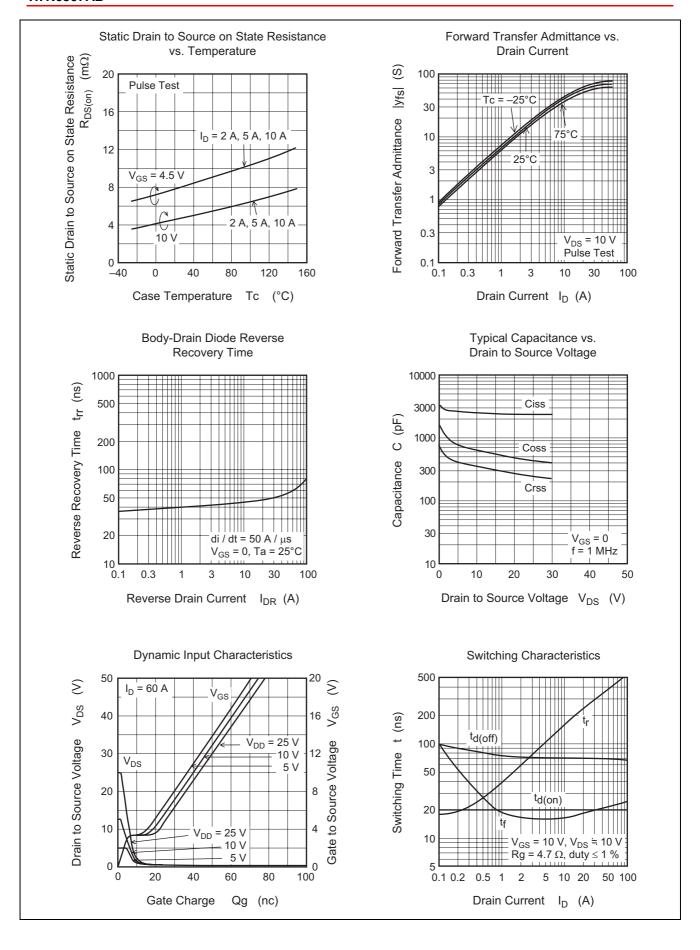
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR) DSS}	30	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR) GSS}	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	10	μΑ	$V_{DS} = 30 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	1.0	_	2.5	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}^{\text{Note 3}}$
Static drain to source on state resistance	R _{DS (on)}	_	4.6	5.8	mΩ	$I_D = 30 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note 3}}$
		_	8.0	11.5	mΩ	$I_D = 30 \text{ A}, V_{GS} = 4.5 \text{ V}^{\text{Note 3}}$
Forward transfer admittance	y _{fs}	40	65	_	S	$I_D = 30 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note 3}}$
Input capacitance	Ciss	_	2500	_	pF	V _{DS} = 10 V
Output capacitance	Coss	_	650	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	350	_	pF	f = 1 MHz
Total gate charge	Qg	_	40	_	nC	V _{DD} = 10 V
Gate to source charge	Qgs	_	7	_	nC	V _{GS} = 10 V
Gate to drain charge	Qgd	_	8	_	nC	I _D = 60 A
Turn-on delay time	t _{d (on)}	_	20	_	ns	$V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}$
Rise time	t _r	_	300	_	ns	$R_L = 0.33 \Omega$
Turn-off delay time	t _{d (off)}	_	70	_	ns	$Rg = 4.7 \Omega$
Fall time	t _f	_	20	_	ns	
Body-drain diode forward voltage	V_{DF}	_	0.92	_	V	$I_F = 60 \text{ A}, V_{GS} = 0$
Body-drain diode reverse recovery time	t _{rr}	_	60	_	ns	$I_F = 60 \text{ A}, V_{GS} = 0$
						$di_F/dt = 50 A/\mu s$

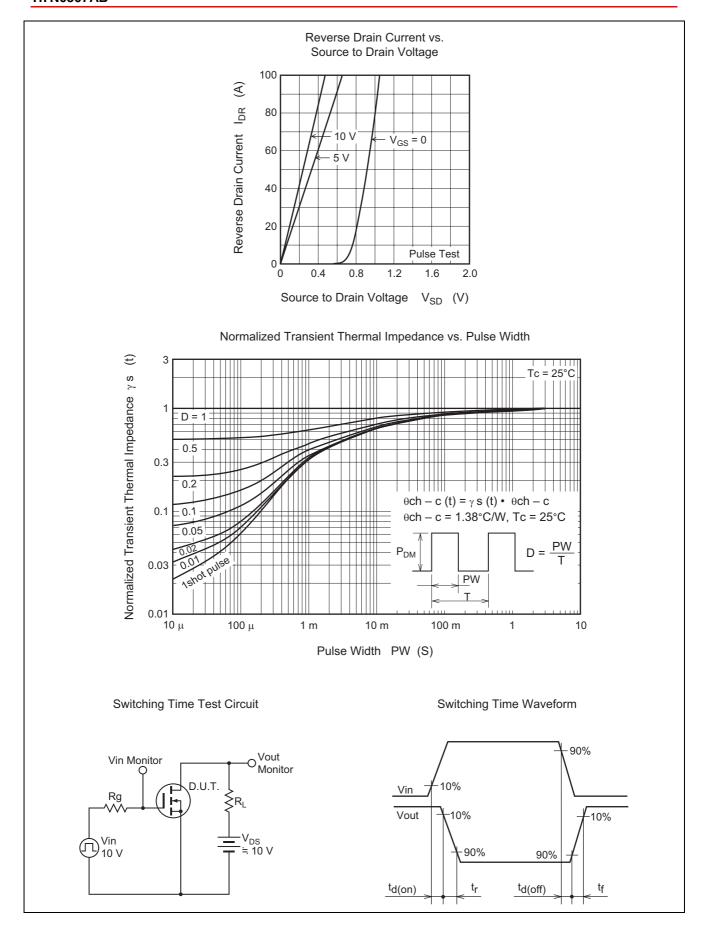
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Note: 3. Pulse test

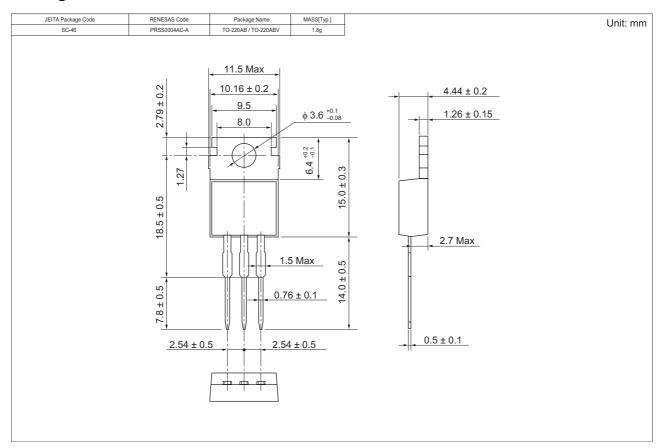
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
H7N0307AB-E	500 pcs	Box (Sack)

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